**ITU - Telecommunication Standardization Sector**

STUDY GROUP 15

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SOURCE[1]: Hatteras Networks

TITLE: Draft Text for liaison to IEEE 802.3ah Task Force

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## ABSTRACT

Draft text to IEEE 802.3ah concerning Ethernet Bonding and use of figures

Subject: T1E1 Bonding Standardization

To: Mr. Howard Frazier, Chairman, IEEE 802.3ah (EFM), Email: millardo@dominetsystems.com
Claudio Stanziola, IEEE-SA Manager of Standards Licensing and Contracts, Email: c.stanziola@ieee.org

CC: Richard Stuart, Rapporteur, Email: rlstuart@ieee.org
Marcos Tzannes, Associate Rapporteur, Email: marcos@aware.com
Barry O'Mahony, IEEE 802.3ah Copper Track Chair, Email: barry.omahony@intel.com

Dear Mr. Frazier,

As discussed in a previous communication, ITU-T Q4/SG15 is advancing a modification of IEEE 802.3ah Ethernet bonding which is generalized to work over other xDSLs. In order to complete the documentation of the Recommendation we respectfully request permission to reproduce the layering diagrams in Figure 61-1 and 61-2 802.3ah, Draft 3.1 (or a likeness thereof).

Thank you for your cooperation.

Regards,

Richard Stuart , Rapporteur Q4/SG15

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[1] Contact: Jerry Radcliffe
Hatteras Networks
T: +1 919 991 5488
E: jradcliffe@hatterasnetworks.com